

**V1.1 Datasheet** 

## N+P 40V MOSFET

## **FEATURES**

- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

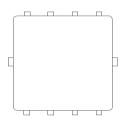
# **Application**

- ■Portable Devices
- ■Consumer Electronics

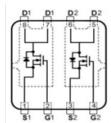
PRODU	CTY SU	MMARY
$V_{DS}$	R <sub>DS(o</sub>	<sub>n)</sub> m(Ω) Max
40	18	@V <sub>GS</sub> =10V
40	22	@V <sub>GS</sub> =4.5V
-40	35	@V <sub>GS</sub> =-10.0V
-40	41	@V <sub>GS</sub> =-4.5V

#### Mechanical

●Case:DFN3333 Package



**DFN3333** 



# **Packing Information**

Package	Packing
DFN3333	5Kpcs/13"Reel

Maximum	n Ratings (T <sub>A</sub> =25°C unl	ess otherwise specif	ied)	
Parameter	Symbol	Lim	it	l lmi4
Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V <sub>DS</sub>	40	-40	V
Gate-Source Voltage	V <sub>GS</sub>	±20	±20	V
Continuous Drain Current 1)	I <sub>D</sub>	15	-12	Α
Pulsed Drain Current 4)	I <sub>DM</sub>	60	-48	А
Maximum Power Dissipation	$P_{D}$	5	5	W
Operating Junction and Storage Temperature Range	$T_J, T_STG$	-55 to 150	-55 to 150	°C

Typical Thermal Re	esistance		
Parameter	Symbol	Limit	Unit
Junction-to-Ambient Thermal Resistance 3)	$R_{\theta JA}$	34	°C/W

#### Note:

- 1. Pulse width<300us, Duty cycle<2%.
- 2. Fused current that based on wire numbers and diameter.
- 3. Guaranteed by design, not subject to production testing.
- 4. The maximum current rating is package limited.
- 5. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}$ =150°C. Ratings are based on low frequency and duty cycles to keepinitial  $T_J$  =25°C.

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Electrical Char	acteristics	(TA=25°C UNLESS OTH	ERWISE	NOTED	)	
Characteristics	Symbol	Test Condition		Limits		Unit
Cital acteristics	Syllibol	rest Condition	Min	Тур	Max	Offic
	١	N-Channel Static				
Drain-Source Breakdown Voltage	$B_{VDSS}$	$V_{GS}$ =0V, $I_D$ =250uA	40	-		V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=250uA$	1.0	1.6	2.0	V
Drain-Source On-State Resistance	О	$V_{GS}$ =10.0V, $I_{D}$ =18A	-	15	18	mΩ
Diam-Source On-State Resistance	$R_{DS(on)}$	V <sub>GS</sub> =4.5V, I <sub>D</sub> =16A	-	19	22	mΩ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1.0	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V	-	-	±100	nA
	Dr	ain-Source Diode				
Maximum Continuous Body Diode Forward Current	Is	-	-	-	1.2	А
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> =1.0A, V <sub>GS</sub> =0V	-		1.5	V

Electrical Char	acteristics	(TA=25°C UNLESS OTH	ERWISE	NOTED	)	
Characteristics	Symbol	Test Condition		Limits		Unit
Characteristics	Symbol	rest Condition	Min	Тур	Max	Onit
	ı	P-Channel Static				
Drain-Source Breakdown Voltage	B <sub>VDSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-40	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=-250uA$	-1.0	-	-3.0	V
Drain-Source On-State Resistance	D	V <sub>GS</sub> =-10.0V, I <sub>D</sub> =-11A	-	30	35	mΩ
Diam-Source On-State Resistance	$R_{DS(on)}$	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A	-	35	41	mΩ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V	-	-	1.0	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V	-	-	±100	nA
	Dı	rain-Source Diode				
Maximum Continuous Body Diode Forward Current	Is	-	-	-	-1.2	А
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> =-1.0A, V <sub>GS</sub> =0V	-	-	-1.5	V

#### Note

- 1. Pulse width<300us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}$ =150°C. Ratings are based on low frequency and duty cycles to keep initial  $T_J$  =25°C.
- 4. The maximum current rating is package limited.
- 5. R<sub>QJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch2 with 2oz.square pad of copper.
- 6. Guaranteed by design, not subject to production testing.

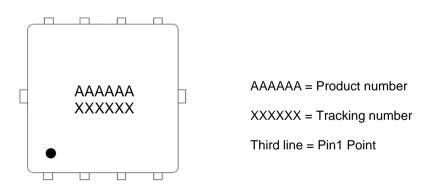
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## Package Outline Dimensions (inches and millimeters)

**	DF	N333	33	
		Dime	nsions	
SYMBOL	Millin	neters	Inc	hes
	Min	Max	Min	Max
Α	0.70	0.80	0.03	0.03
b	0.25	0.35	0.01	0.01
С	0.10	0.25	0.00	0.01
D	3.25	3.45	0.13	0.14
D1	3.00	3.20	0.12	0.13
D2	1.78	1.98	0.07	0.08
D3		0.13	150	0.01
E	3.20	3.40	0.13	0.13
E1	3.00	3.20	0.12	0.13
E2	2.39	2.59	0.09	0.10
е		0.65	BSC	5
Н	0.30	0.50	0.01	0.02
L	0.30	0.50	0.01	0.02
L1	0.	13	1020	0.005
K	0.30		0.01	
θ	-	12	5±1	12
M	. 8	0.15	844	0.01

#### **Marking Information**



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